

2014 CSR Report



GlobalWafers Japan



CONTENTS

Corporate Philosophy, Management Policy, and Message from the CEO	... P1
Introduction of our product	... P2 ~ 3
Our internal control basic policy and compliance structure	... P4
BCP (Business Continuity Plan)	... P5
Respecting human rights and developing work environment where everyone feels comfortable working at	... P6 ~ 7
Environmental report	... P8 ~ 10
Contributing for the regional community / society	... P11

Corporate Philosophy

Become a world-class advanced semiconductor materials manufacturer to serve our stakeholders including customers, employees, shareholders, and a harmonious society with our excellent products and continuous technology development.

Management Policy

1. Customer Satisfaction
Contribute to our customers by providing solutions with products and services responding to our customers' requirements
2. Faithful Corporate Activities
Comply with global and domestic laws and regulations, correspond to all stakeholders faithfully and equally, and contribute to protect the global environment.
3. High Level of Professionalism
Improve capabilities and creativities of our employees to encourage to have high level of expertise and professionalism.
4. Excellent Teamwork
Foster open corporate culture, strengthen collaborative activities among employees at different organizations, and work on challenging tasks in excellent teamwork.
5. Sustainable Growth
Aim for everlasting growth through consistent innovation in technology development, business strategies, and management.



Message from the CEO

GlobalWafers Japan has become a member of Sino-American Silicon Products Inc. (Taiwan) in 2012, and had made a fresh start from January 2013 under the new company name of GlobalWafers Japan Co., Ltd.

Currently GlobalWafers Japan is working on manufacturing products whose bases are for providing "the quality and services in accordance with the customers' needs" to the people around the world in order to provide a rich future via the silicon wafer business which will be the basis

for the semiconductor industry together with our group companies operating mainly in Japan, the U.S., Taiwan, and in China.

We are pleased to inform you that GblalWafers Japan has been able to prepare a CSR Report thanks to the guidance provided by various customers. We consider it essential that in order to be able to have business with the customers all over the world, we nurture a corporate culture based on the Electric Industry Code of Conduct (CSR alliance for the electronic industry) which is expected to be an international standard.

GlobalWafers Japan and all persons relevant with it have been operating and promoting the development of its compliance structure, information management structure, risk management structure, BCP (business continuity plan), and internal control structure based on its internal control basic policies and business actions standards in order to achieve our corporate philosophy and management policy, and we are hoping to further promote our CSR activities so that we can contribute not only for the regional community but also for the entire world. We would appreciate your continued guidance and cooperation.

January 1, 2015

Toru Masaoka
President & Representative Director



CSR Promotion Structure

◆ We will develop and provide products that are socially useful and safe to achieve satisfaction and trust from our customers.

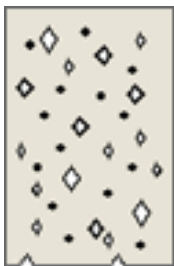
- (1) We will provide products and services that are valuable and are satisfactory from all aspects of quality, cost, and delivery timing.
- (2) We will respond to our customers' requests in a sincere and accurate manner while also providing accurate product information to exercise our quality assurance responsibilities.
- (3) We will supply the state-of-art products with superior added value to the market by tireless technologies development efforts and therefore contribute for the development of a sustainable society.
- (4) We will exercise our own business in a fair and sincere manger with our acknowledgement and responsibilities as a professional company, and will also continuously work upon self-improvement and improvement in the quality of our business.

■ Introduction of our product (lineup)

Products	Type	Use	4"	5"	6"	8"	12"
"ECAS®" Series Engineered wafers	ECAS®-A	MOS IC, LSI, Memory (DRAM,NAND) Logic Analog CMOS Image Sensor					○
	ECAS®-C					○	
	ECAS®-V					○	
	ECAS®-Z					○	
Polished wafers	Prime wafers	MOS IC, LSI Analog				○	○
Annealed wafers	Hi-WAFER®					○	
	Hyper Hi-WAFER®					○	
	AT-WAFER				○	○	
Epitaxial wafers	N/N+ (As,Sb,Phos)	Discrete Devices; Small Signal Pw Transistor IGBT		○	○	○	
	P/P+			○	○	○	
	N/P		○	○	○	○	
	N/N+/P+			○	○	○	
	N/P BL=N+P+	Bipolar IC	○	○	○		
Diffused wafers	N-/P+	Discrete Devices; Pw Transistor IGBT	○	○	○		
	N-/N+		○	○	○		
	P-/P+ Power Transistor		○	○	○		
SOI wafer	N/SiO₂/N	MEMS & PowerDevices	○	○	○		
	P/SiO₂/P		○	○	○		

■ GlobalWafers Japan provides various wafers manufactured under the consistent production and quality control structure starting from the single crystal pulling stage, surface treatment stage, washing stage, and the packaging stage to respond to the expectations made by our users by the stable quality of the products provided.

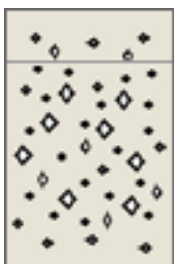
■ Type of Silicon Wafers



Polished Wafers

Polished wafers are silicon wafers with one or both sides polished to a mirror surface. Our polished wafers are superior in properties such as flatness and cleanliness. They have earned an excellent reputation for high quality and precision that meets the needs of the ULSI age.

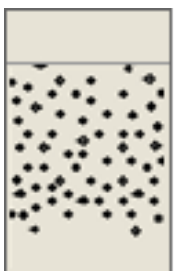
- ◇ COP(Void, grown-in defect)
- BMD(oxygen precipitates)



Hi-WAFER®

Hi-WAFER®(Hydrogen Annealed Wafer) is heat treated in hydrogen ambient, and realized high BMD density which provides gettering ability as well as COP-free zone in the wafers surface region. These properties contributes to have excellent gate oxide quality.

- ◇ COP(Void, grown-in defect)
- BMD(oxygen precipitates)



Hyper Hi-WAFER®

Hyper Hi-WAFER® has been developed for high-end devices with finer technology node. The wafer is also annealed in Hydrogen atmosphere like Hi-WAFER®, but has smaller, well controlled BMDs and better surface integrity than Hi-WAFER®.

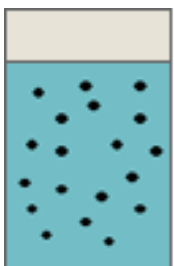
- ◇ COP(Void, grown-in defect)
- BMD(oxygen precipitates)



AT-WAFER (Ar Treatment Wafer)

AT-WAFER is also an annealed wafer, but heat treated in Argon gas ambient to prevent outdiffusion of dopant from wafer surface and to have flat resistivity profile in depth. AT-WAFER serves the same quality as Hyper Hi-WAFER® in other aspects.

- ◇ COP(Void, grown-in defect)
- BMD(oxygen precipitates)



Epitaxial Wafers

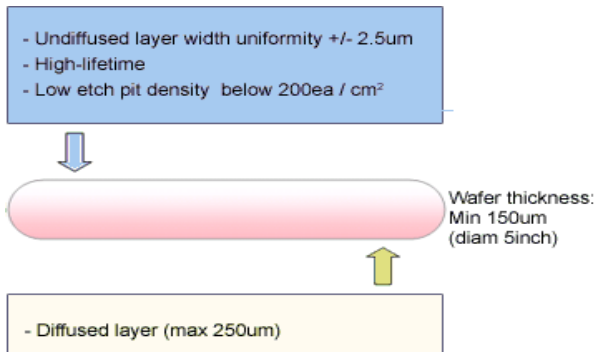
Epitaxial wafers are the traditional wafers to achieve surface integrity by putting various thickness epitaxial silicon layers. Thin Epi wafers are commonly used for leading edge MOS devices. Thick Epi or Multi-layered epitaxial wafers are used for the devices mainly to control electric power, and they are contributing to improving the efficiency of energy consumption.

- ◇ COP(Void, grown-in defect)
- BMD(oxygen precipitates)

Diffused Wafers

Diffused wafers are employed in electric power control devices at a high rate, and contribute to improving the efficiency of energy consumption.

Structure of Diffused wafer



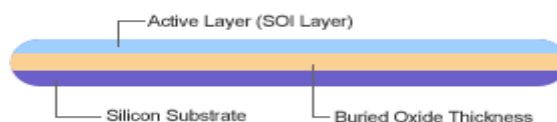
Features of Diffused Wafers

Diameter	4,5,6inch
Crystal Method	MCZ(Doped), MCZ(NTD), CZ
Crystal direction	(100), (111)
Type	P+(Boron), N+(Phos)

SOI(Silicon On Insulator)Wafer

Thick SOI wafers are widely used in power devices and MEMS to achieve high breakdown voltage, low energy consumption and high performance of MEMS. This is possible due to their SOI structure. We use a bonding method in the manufacture of thick SOI wafers and exercise more precise control over the thickness of the SOI layer and the BOX layer. The demand for SOI wafers in leading-edge devices such as intelligent power modulus, which require high breakdown voltage and low energy consumption, is also increasing. More over MEMS made of SOI brings complex 3-D structure such as accelerometer and pressure sensor.

Structure of SOI (Silicon-On-Insulator) Wafers



Features of Our SOI Wafers

	100mm	125mm	150mm
Diameter	100mm	125mm	150mm
Surface orientation	(100), (111), (110)		
Type(Dopant)	N(Phos., As, Sb), P(Boron)		
Active layer thickness	2.0-200.0µm		
Tolerance of active layer thickness	±0.3 *		
Buried oxide thickness	±2.0 *		
Tolerance of buried oxide thickness	±5%		
Handle wafer thickness	200 – 625µm	300 – 665µm	

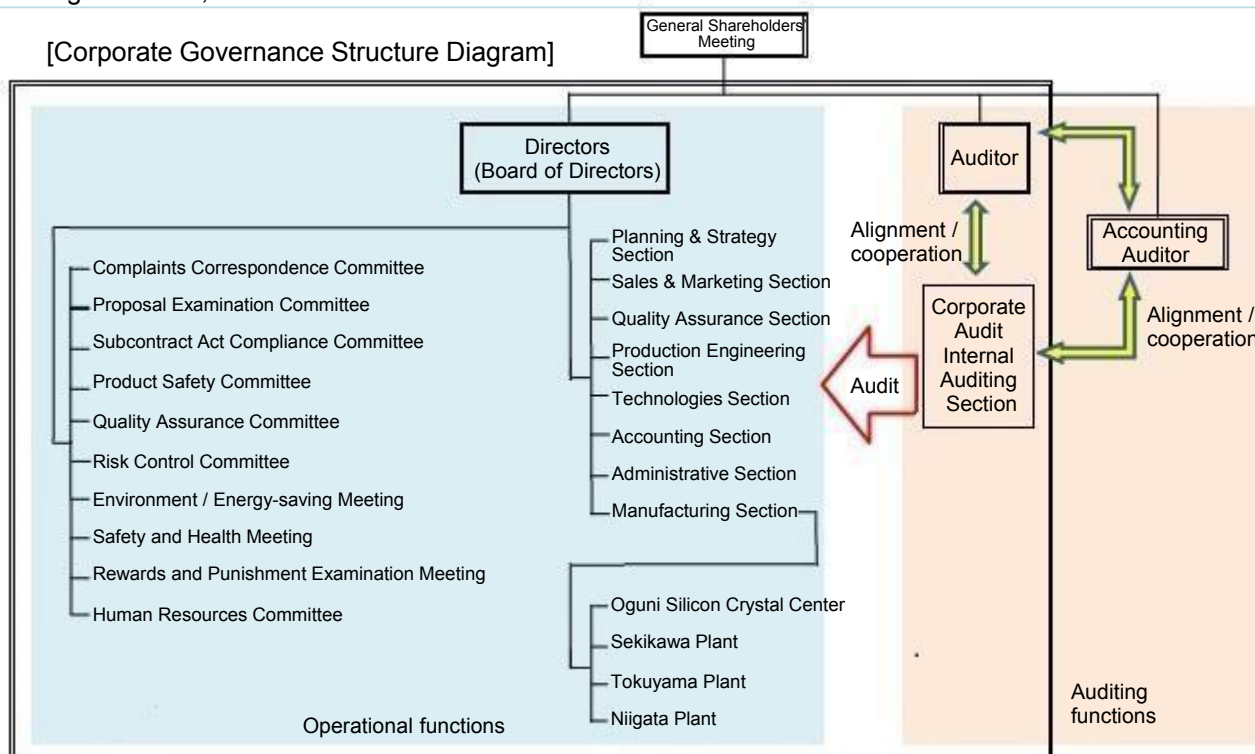
* For further requirements, please contact us.

◆ Our internal control basic policy and compliance structure

We will act in compliance with the laws and contract, and will implement adequate transactions under fair and free competitions.

- (1) We will communicate with all or our customers in a fair and just manner and implement transactions under appropriate conditions.
- (2) We will comply with the Act on Prohibition of Private Monopolization and Maintenance of Fair Trade, the Unfair Competition Prevention Act, and the Subcontract Act, etc., implement transactions by following sound business practices and social standards, and will not provide or receive any profit that is inappropriate from the legal or social standard perspective
- (3) We will comply with the Patent Act, the Copyright Act, and other law and internal regulations regarding intellectual properties to work upon obtaining, protecting and utilizing our intellectual properties, and will value legitimate intellectual properties rights of the third parties.
- (4) We will comply with the laws regarding export control for the countries and regions we operate our businesses in, and will not be relevant with any transaction of the goods or technologies that may inhibit maintenance of the international peace and safety whose export are restricted. Additionally, we will make sure no conflict mineral is used.
- (5) We will make sure that not only GlobalWafers Japan but also those within our supply chain will not be relevant with any antisocial force or groups that would threaten the order and safety of the civil society.
- (6) We will maintain sound and proper relationships with politicians, politic organizations, and administrative organizations, etc.

[Corporate Governance Structure Diagram]



■ GlobalWafers Japan acknowledges that the responsibilities for the Board of Directors and the management are to adopt the internal control basic policy at the Board of Directors and to firmly maintain and operate the internal control system.

The purposes are;

- (1) to ensure business efficiency and results (profitability, performances, and asset maintenance)
 - (2) to ensure reliability of the financial reports,
 - (3) to submit reasonable grounds for guaranteeing the achievement of compliance to the laws.
- In order to make internal control even more effective, audit is implemented by auditors, accounting auditors, and the Corporate Audit.

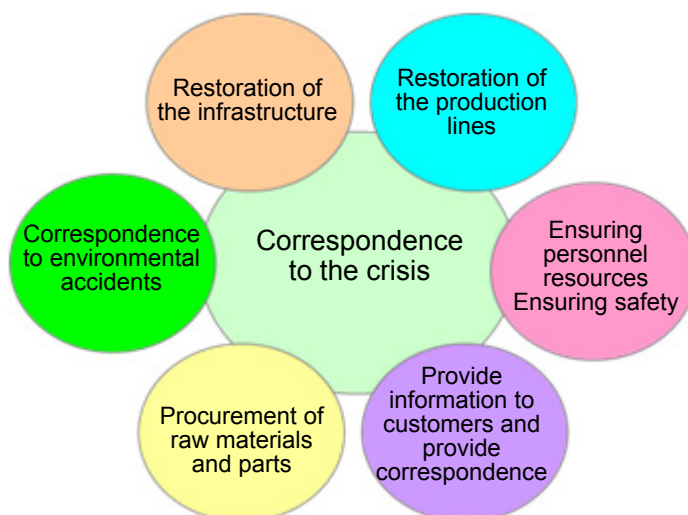
■ Information protection / management and communication

GlobalWafers Japan will appropriately protect and control company information, etc., and will also implement appropriate communication and information disclosure in order to gain accurate understanding and reliance from all stakeholders.

- (1) We will handle trade secrets and personal information, etc. of GlobalWafers Japan and other third parties in an adequate manner, and will take appropriate measures in order to prevent from having such information disclosed, leaked, used, or tampered in an inappropriate manner.
- (2) During both while being hired by and after resigning from GlobalWafers Japan, no employee or company member will collect, disclose, leak, or use any trade secret or personal information of the company's or of any other third party in an appropriate manner.
- (3) We will disclose our company information such as our management policy, business contents, financial reports, and the situations occurred, etc. in a fair manner based on objective facts, and will obtain accurate understanding and reliance from our customers, shareholders, clients, and regional community, etc.
- (4) We will not be relevant with any insider trading such as selling and purchasing securities based on non-disclosed company information.

◆BCP (Business Continuity Plan)

GlobalWafers Japan is working upon being prepared for various assumed risks for business continuity crises, and has determined the organizational structure, roles and responsibilities, and procedures for making the damages for the customers, clients, employees, regional community, and all relevant persons minimum within the Business Continuity Plan.



■Chart of business continuity crises assumed

Business premise	HQ / Niigata Plant	Tokuyama Plant	Sekikawa Plant	Oguni Silicon Crystal Center	Tokyo Office	Hadano Site
Location	Niigata Pref.	Yamaguchi Pref.	Niigata Pref.	Yamagata Pref.	Tokyo	Kanagawa Pref.
Earthquake	○	○	○	○	○	○
Tsunami	○	○	-	-	○	-
Flood	○	○	○	○	○	○
Snow damage	○	-	○	○	-	-
Fire	○	○	○	○	○	○
Mass infection	○	○	○	○	○	○
Terrorism	○	○	○	○	○	○

■Provide information to customers

In case any large-scale natural disaster, etc. occurs that may impact supplying the products to our customers or that may let our customers be concerned due to the media coverage, etc., the Sales & Marketing section will collaborate with the subject manufacturing site, and immediately communicate with our customers as for the required matters etc. such as the disaster occurrence status, damage status, and the impact onto the product delivery, etc.

■Ensuring personnel resources / ensuring safety

We will place the highest priority onto ensuring the safety of all relevant persons based on the prerequisite of valuing human lives the most, will develop a communication structure for the emergency support team, and will develop the alignment / cooperation structure between each plant in order to ensure personnel to enable restoration.

■Materials procurement activities (raw materials, parts)

We will promote procurement from multiple vendors, and as for the raw materials / parts that cannot be procured from multiple vendors, we will basically utilize our stock raw materials / parts where we determine our stock amount based on the delivery timings, etc. In case any disaster such as an earthquake occurs, we make sure to confirm what impact there may be from the vendor's side.

■Correspondence to environmental accidents

In compliance with the Environmental Accident Correspondence Regulations, we will work upon minimizing the occurrence of environmental accidents, and will ensure to make reports to the regional residents and alignment with various administrative organizations in order to minimize the impact onto the regional environment.

■Restoration of the infrastructure

Each plant will ensure the minimum required power source by utilizing emergency power generators in order to ensure safety, and especially at Niigata and Tokuyama plants, a supply structure which is resilient against natural disasters is being established together with each supplier. Additionally, a hotline is being developed in between the suppliers to be fully prepared to ensure the required infrastructure.

■Ensuring the transportation routes

We have established a structure where multiple transportation measures are ensured in between our customers and each of our plants.

Domestic transportation: Ensuring multiple transportation routes

International transportation: Developed a transportation structure where several airports are being used (including the customs procedure)

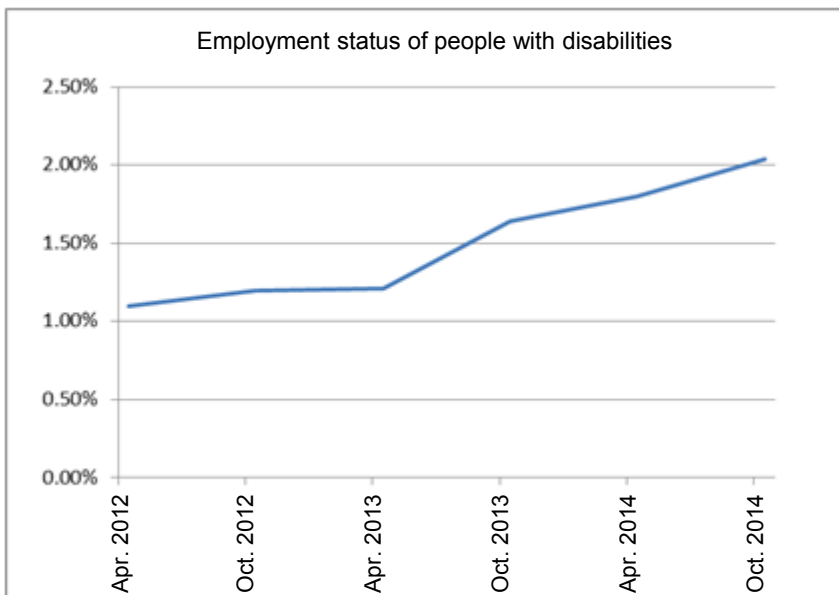
◆Respecting human rights and developing work environment where everyone feels comfortable working at
 We will respect the human rights, personality, and diversity of our employees, will develop safe work environment where the employees would feel comfortable working at in order to realize ease of mind and affluence.

- (1) We will respect the fundamental human rights and various senses of value, personality, and privacy, will stay away from any violence, abusive languages, various harassments, or any discrimination based on the difference of race, religion, gender, nationality, or physical ability/disability, etc., and will work upon nurturing an open corporate culture.
- (2) We will provide appropriate wages and control the work time in an appropriate manner, and will make sure to abolish any forced labor, child labor, inhumane treatment, or violation of human rights, not only within GlobalWafers Japan but also within our entire supply chain, too.
- (3) We will realize a comfortable work environment where health and safety of the employees and people relevant are taken into consideration so that we can work upon preventing any industrial accident or occupational disease, and we will develop emergency countermeasures against natural disasters, etc.

■Promotion of the employment of people with disabilities

Our rate of employment of people with disabilities as of April 2012 was approx. 1%.

Since then, we have been working upon improving such rate as our top priority, and thanks to the cooperation provided by the Labor Bureau, the Employment Security Office, and the local region, we have been able to surpass the statutory employment rate in October 2014. We will aim to further improve this rate in the future, too.



■Industrial safety and health activities

As for the safety and health activities, we have established and are promoting a system based on OSHMS (Operational Safety and Health Management System). Every year, we would review our activities for the previous year to determine the company-wide priority matters for the safety and health activities. We also implement safety and health audit at each plant once a year.

At Oguni Silicon Crystal Center, we have achieved a record of not having any disaster for consecutive 3000 days (and still extending the record number of days) as of January 2014, and have been rewarded as a "an Office Superior for Safety Management" at the Safety and Health Competition for the Okitama district in Yamagata Prefecture.

As for mental health prevention measures, we have established a counseling system to promotion developing the environment where the employees would feel easier to get any counseling.

2014 Company-wide priority matters for the safety and health activities

1. Initiative to aim for zero labor accidents
 - 1) Ensuring KY (Kiken Yochi – danger prediction)
 - KY checks immediately before work execution: Hold KY check meetings, implement personal KY checks, and making it a daily custom to "point-and-call"
 - Implement regular KYTs (fully utilize disaster examples in the past and near-miss reports, etc.)
 - Identifying, labelling, and implementing countermeasures for the defects for the works and facilities
 - 2) Ensuring risk assessment
 - Assess risks at times of changing the processes or when implementing safety measures
 - Immediate improvement level III and IV
 - 3) Continuous implementation of safety sensory education
 - Implementing sensory education in a planned manner
 - Introduce sensory education that can be prepared easily in a planned manner
2. Implementation of the mental health prevention measures
 - 1) Education on the cares by self-care and by the line
 - All subject members to have the education provided in a planned manner
 - 2) Develop an environment where the members would feel easier to get the counseling

■Record of not having any disaster

	Disaster occurred on;	Date or record;	Number of days with no disaster	Years	Months	Days
Niigata Plant	Aug. 20, 2014	Dec. 31, 2014	133 days	0	4	11
Tokuyama Plant	Oct. 1, 2013	Dec. 31, 2014	456 days	1	2	30
Oguni Silicon Crystal Center	Sep. 12, 2005	Dec. 31, 2014	3,397 days	9	3	19
Sekikawa Plant	Mar. 11, 2014	Dec. 31, 2014	295 days	0	9	20



■ Disaster prevention drills

Comprehensive disaster prevention drills are held at each site such as the HQ and Niigata Plant, etc. in order to be fully prepared for emergency cases.



↑ Evacuation drill held at the HQ / Niigata Plant



↑ Evacuation drill at the HQ / Niigata Plant using a ladder vehicle



↑ Emergency life-saving drill held at Sekikawa Plant



↑ Life-saving treatment by the emergency life savers at Oguni Silicon Crystal Center



↑ Disaster prevention drill held at Tokuyama Plant (with the cooperation of the fire station)



↑ Water discharge exercise at Tokuyama Plant

■ Ensuring risk assessment

During 2014, we assessed the risks not only during normal works but by focusing on assessing the risks for when changing the process and during abnormal works in order to work upon reducing the risks.

Risk level assessment standards

Risk level IV: There is a problem that needs to be resolved immediately

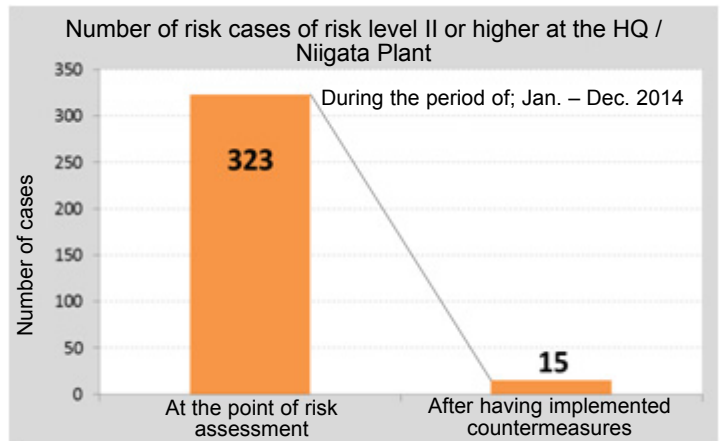
(To be canceled or improved immediately)

Risk level III: There is a serious problem (to be improved with higher priority)

Risk level II: There is some problem (to be improved in a planned manner)

Risk level I: Risks to be reduced as necessary

(Education to be provided according to the remaining risks)



◆ Environmental report

For the purpose of protecting the irreplaceable global environment and of handing over it in a sound state, we will act upon environmental conservation activities in a sincere manner

■ Environment Policy

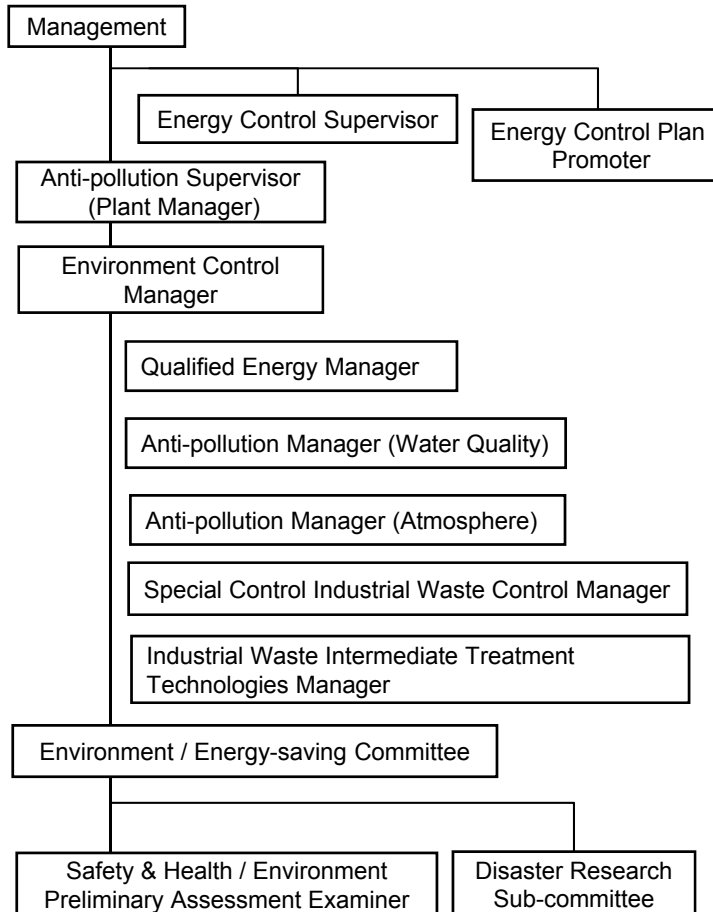
Slogan

“As a semiconductor materials manufacturer with cutting-edge technologies, we will continuously promote our initiatives for environment conservation via manufacturing products at a global scale, and therefore exercise or social responsibilities so that we can contribute in realizing a sustainable society.”

1. We will position our initiatives for environmental conservation as one of our focus issues for our business operation.
2. We will comply with the environment-related laws, other requires we have agreed upon, and other self-management standards.
3. As for the environmental aspect relevant with our business activities, we will implement improvement in a continuous manner in order to make an effort to prevent any environment contamination.
4. We will set environmental purposes and targets in order to roll out our environment policy, and will work upon reducing our CO₂ emission to prevent global warming, upon reducing the amount of industrial waste, and reducing the amount of restricted chemical substances used.
5. We will work upon maintaining and preserving the soundness of the natural environment and of the biological diversity.
6. We will promote green procurement, and will make an effort to purchase raw materials with less environmental load.
7. We will contribute for the society via developing and providing superior environmental technologies and environment-friendly products, via cooperation and alignment with the local region and the society, and via environment conservation activities.
8. This Environment Policy will be documented, fully notified to all employees including those for the relevant companies within the premise and other partner companies, etc., be maintained by each organization without fail, and will be openly disclosed to the public.

■ The structure for promoting environmental control and anti-pollution

GlobalWafers Japan acknowledges that environment conservation is one of its management issues, and has a structure for promoting environment control established for the purpose of effectively implementing continuous improvement activities and the PDCA cycle in order to ensure environment conservation.



■ Focus themes

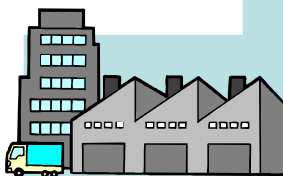
We have stipulated the target to reduce the CO₂ emission, industrial waste amount, and the amount of chemical substances used (PRTR) by 5% each in 2015, and are promoting the activities for achieving the target.

Focus themes	Self-action plans
Reduction of CO ₂ emission	In order to achieve “reducing 1% or more of energy consumption unit for the annual average” stipulated by the Act on the Rational Use of Energy, we will reduce CO ₂ emission by implementing the energy-saving activities in compliance with the mid- to long-term plan submitted to the METI.
Reduction of industrial	We will suppress the generation of the waste that occurs according to our business activities, promote recycling of them, and promote reduction of the final disposal amount.
Reduction of the amount of chemical substance used	We will reduce the amount of substances subject for PRTR with significant environmental impact level.

■ Material balance Data collected during; Apr. 2013 – Mar.2014

Input

Electric energy : 256,983,767 kw
 Town gas : 3,078,867 Nm³
 Heavy oil: : 183,816 kℓ
 Industrial water : 4,299,174 m³
 Water supply : 39,143 m³
 Chemical substance : Hydrofluoric acid, sulfuric acid, hydrochloric acid, and hydrogen peroxide, etc.



Output

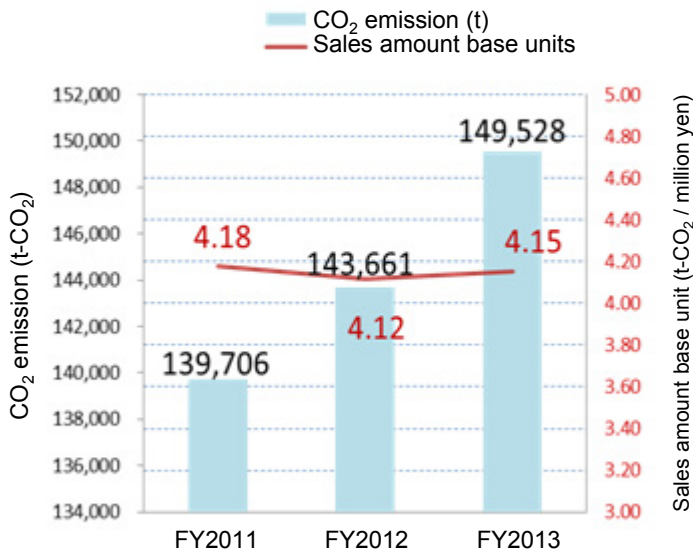
Product : Silicon wafer
 CO₂ emission : 149,528t – CO₂
 Displacement : 266,045 m³
 Industrial waste amount : 6,236,991 kg

The measured data for emission to atmosphere and the displacement measured data results were all below the statutory level

■ Promotion of energy-saving

In order to continuously reduce CO₂ emission, the plants are implementing energy-saving initiatives such as improving productivity at plants and introducing energy-saving machineries.

CO₂ emission / sales amount base unit



■ Energy-saving efforts

◎ Niigata plant has been able to reduce CO₂ emission by approx. 10% for the period until FY2013 by implementing the measures of enabling inverter for utilities, reviewing the maintenance method, and optimizing the manufacturing process, etc.

◎ We are implementing improvement activities to identify whether we are not wasting any electricity, or whether we can reduce the amount of electricity we are using, etc.

◎ We are promoting modal shift (changing transportation method from vehicle transportation to railway transportation).

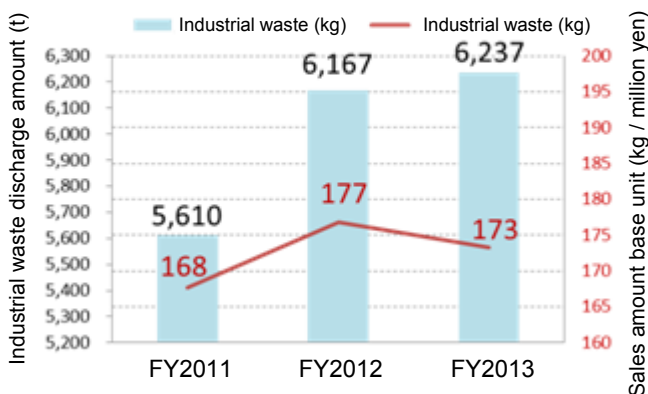


Energy-saving patrol activity: Niigata plant

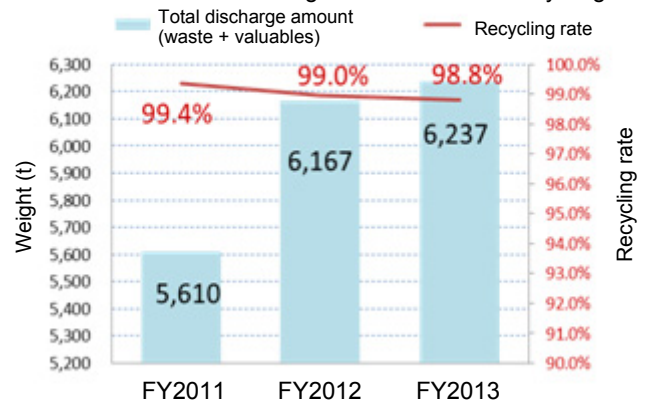
■ Promotion of suppressing waste generation

In order to establish a sustainable recycling society, we are working upon improving our production efficiency, effectively utilizing resources, and recycling of the resources by ensuring thorough sorting of the waste, therefore making an effort to reduce the amount of waste.

Industrial waste discharge amount / sales amount base unit



Industrial waste total discharge amount and the recycling rate



■ Improvement example of the promotion of suppressing waste generation

We have changed the boxes used for shipping our products to our customers from single-use cardboard boxes to returnable boxes, and then to container boxes to be able to reuse them.



Cardboard box
(which contains 1 case (25 units)
of 300mm wafers)



Returnable box
(which contains 1 case (25 units)
of 300mm wafers)

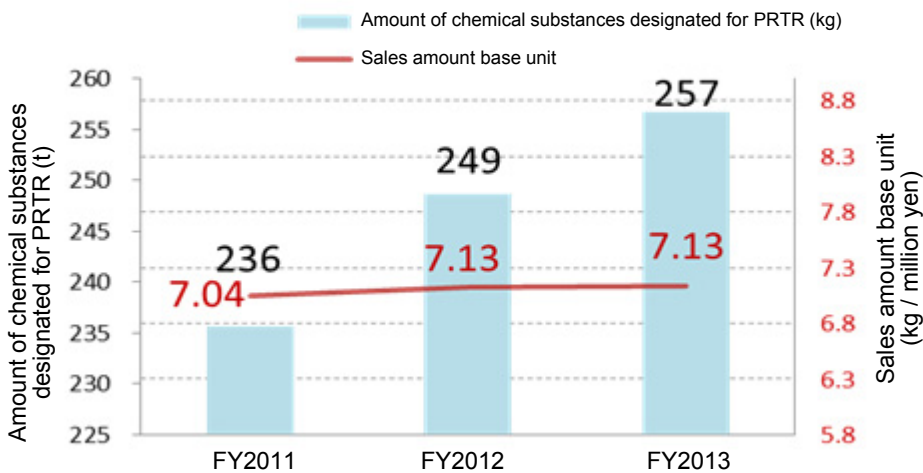


Container box
(which contains 12 cases (300 units)
of 300mm wafers)

■ Promotion of suppressing the usage of chemical substances (substances subject for PRTR)

In order to reduce the environmental risks that would be generated by using toxic chemical substances and therefore would lead onto the contamination of the natural environment and to health damage, we are working upon abolishing the usage of and reducing the usage amount of the toxic chemical substances, and upon shifting to using substitute products.

Amount of chemical substances designated for PRTR / sales amount base unit



Target: Substances subject for PRTR (Pollutant Release and Transfer Register)

PRTR (Pollutant Release and Transfer Register) is a system to acknowledge, calculate, and disclose the data regarding how much various toxic chemical substances were discharged from which origin, or how much of them were delivered to out of business premises by being included into wastes.

Pollutant release and transfer (substances subject for PRTR)

Unit: kg

Name of chemical substance	Amount handled	Total	Amount discharged				Transferred amount		
			Diffused to atmosphere	Discharged water	Discharges soil	Landfill disposal within business premise	Total	Discharged to sewerage	Discharged as waste
FY2011	235,660	2,834	1,954	880	0	0	3,910	310	3,600
FY2012	248,581	2,609	2,039	570	0	0	3,583	330	3,253
FY2013	256,694	2,613	2,133	480	0	0	3,420	328	3,092

■ Protecting the environment together with the regional community



Tokuyama plant implemented the activity for picking up trashes and weeding along Tonda River which is located in front of the plant as part of its monthly environmental events. There are much less amount of trashes left within the area. We will continue with this activity in the future, so that the people in the regional community and the people commuting to the plant can feel comfortable when passing by the plant



Members at the HQ / Niigata plant participated in Seiro Town's "Town Clean-up Operation" The event is a superb opportunity to realize how much trashes are being thrown away and how much it is important to make our own environment cleaner by picking up the trashes from around our own office / plant.

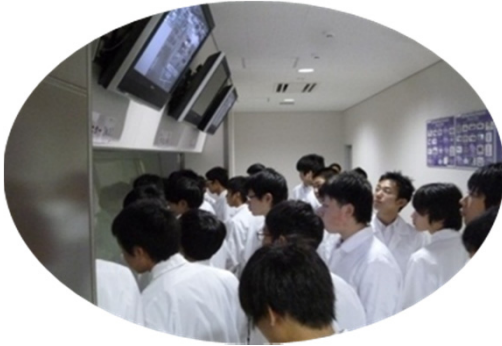
◆Contributing for the regional community / society

We will implement social contribution activities as a good corporate citizen, and will exercise our responsibilities as a member of the regional society.

Especially for the purpose of developing the younger generation who will take on the central role for the next generation, we have established our action plan based on the Act on Advancement of Measures to Support Raising Next-Generation Children, and are implementing the plan at each business premise in an active manner in corporation with the regional communities.

HQ / Niigata plant

Niigata Prefectural Shibata High School “The Future Brilliance Plan” – visiting Niigata plant



Lecture at Yamagata Prefectural Oguni High School
[Message from professional people]



Oguni Silicon Crystal Center
Junior high school students visiting the Center
for “experiencing familiar jobs”



Tokuyama plant
High school students (at Tokuyama Technical High School)
Visiting the plant for its “experiencing and learning”
curriculum



Sekikawa plant
Students at Sekikawa Elementary School visiting
the plant





6-861-5, Seiro-machi Higashiko, Kitakanbara-gun, Niigata, 957-0197
General Affairs

Tel.: (Representative No.): 025-256-3200

Web site: <http://www.sas-globalwafers.co.jp/>

2014 CSR Report, GlobalWafers Japan Co., Ltd.: Issued in January 2015